

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

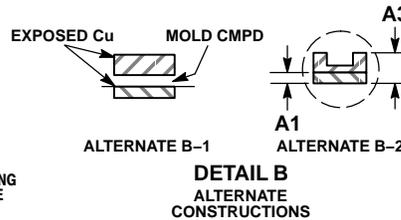
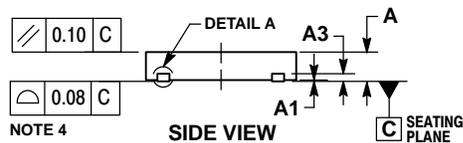
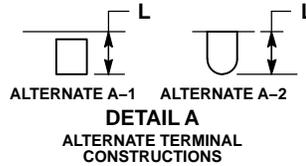
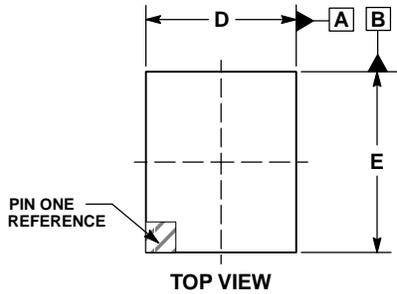
ON Semiconductor®



SCALE 2:1

DFN6 5x6, 1.27P
CASE 506DV
ISSUE O

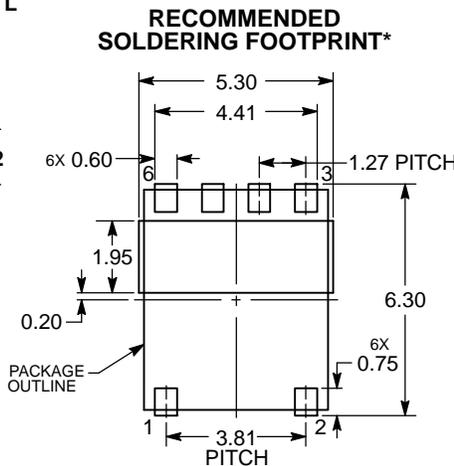
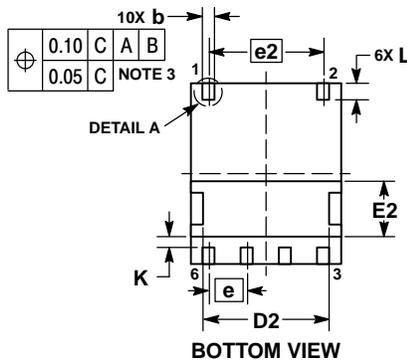
DATE 12 OCT 2016



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. FOR DEVICE OPN CONTAINING W OPTION, DETAIL B ALTERNATE B-1 AND DETAIL A ALTERNATE A-1 CONSTRUCTIONS ARE NOT APPLICABLE.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	---	---	0.05
A3	0.20 REF		
b	0.30	0.40	0.50
D	4.90	5.00	5.10
D2	4.10	4.20	4.30
E	5.90	6.00	6.10
E2	1.75	1.85	1.95
e	1.27 BSC		
e2	3.81 BSC		
K	0.25	---	---
L	0.45	0.55	0.65



DIMENSIONS: MILLIMETERS

GENERIC MARKING DIAGRAM*



- A = Assembly Location
- LL = Wafer Lot
- YY = Year
- WW = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
DESCRIPTION:	DFN6 5X6, 1.27P	PAGE 1 OF 2

